

[illegible]

A semiconductor package is ^{includes} comprised of a substrate for mounting and fixing a semiconductor ^{chip} ~~element~~ thereon and a connecting pattern. The substrate is provided with a through ^{elongate opening} ~~hole~~ formed therein. The semiconductor ^{chip} ~~element~~ is fixed with its surface ~~where the element is formed~~ being mounted on the substrate and with its electrode being within the ~~through hole~~. The electrode of the semiconductor ^{chip} ~~element~~ is electrically connected to the connecting pattern via wires ^{aligned elongate opening} ~~through the through hole~~. The ^{chip} ~~through hole~~ and the wires are sealed with resin.